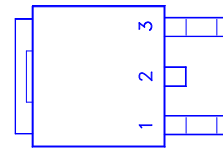
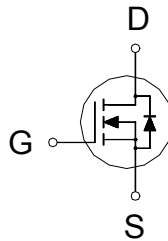


**PRODUCT SUMMARY**

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
40V	25mΩ	32A



1. GATE
2. DRAIN
3. SOURCE

**100% Rg tested  
100% UIS tested**

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	40	V
Gate-Source Voltage		$V_{GS}$	±20	V
Continuous Drain Current	T <sub>C</sub> = 25 °C	$I_D$	32	A
	T <sub>C</sub> = 100 °C		20	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	70	
Avalanche Current		$I_{AS}$	17	
Avalanche Energy	L = 0.3mH	$E_{AS}$	44	mJ
Power Dissipation	T <sub>C</sub> = 25 °C	$P_D$	41.6	W
	T <sub>C</sub> = 100 °C		16.6	
Operating Junction & Storage Temperature Range		T <sub>j</sub> , T <sub>stg</sub>	-55 to 150	°C

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		3	°C / W
Junction-to-Ambient	$R_{\theta JA}$		75	°C / W

<sup>1</sup>Pulse width limited by maximum junction temperature.

**ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25 °C, Unless Otherwise Noted)**

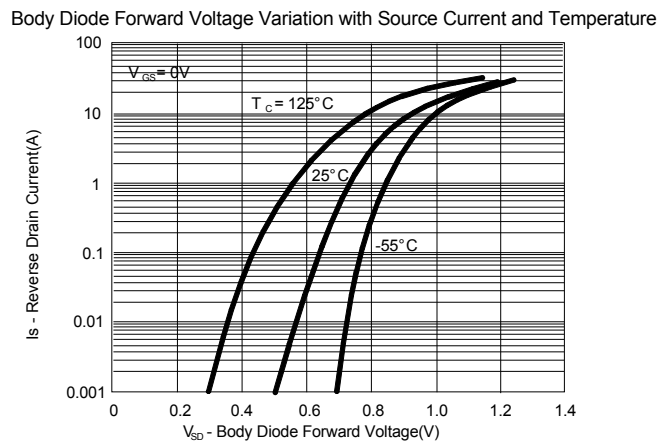
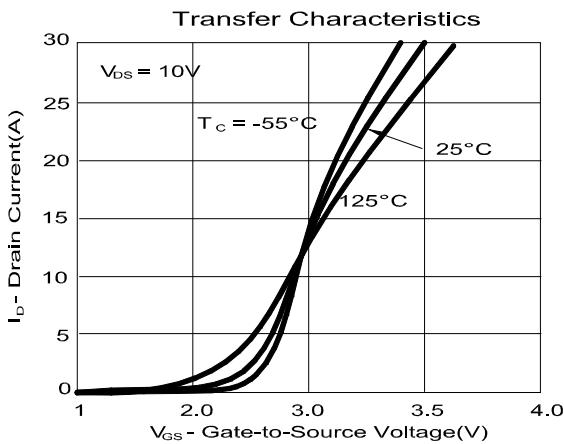
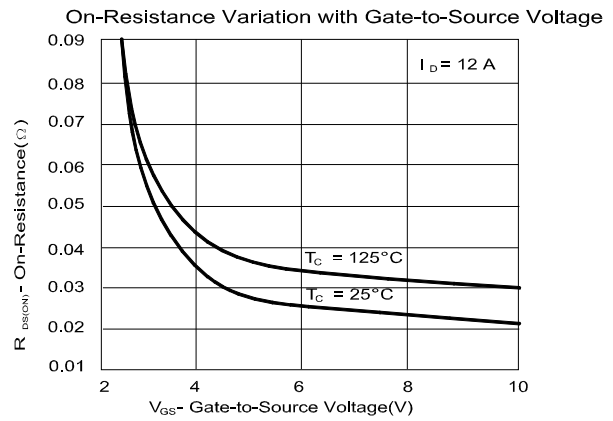
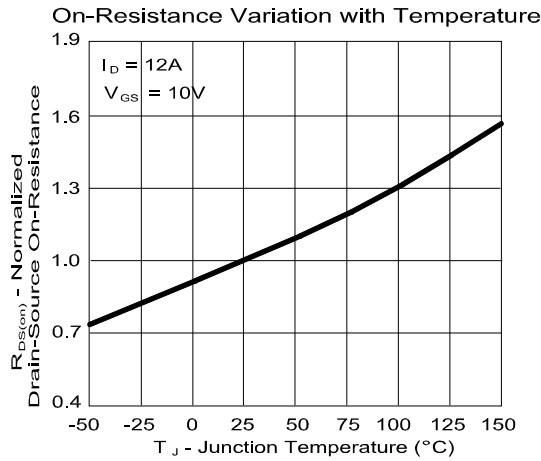
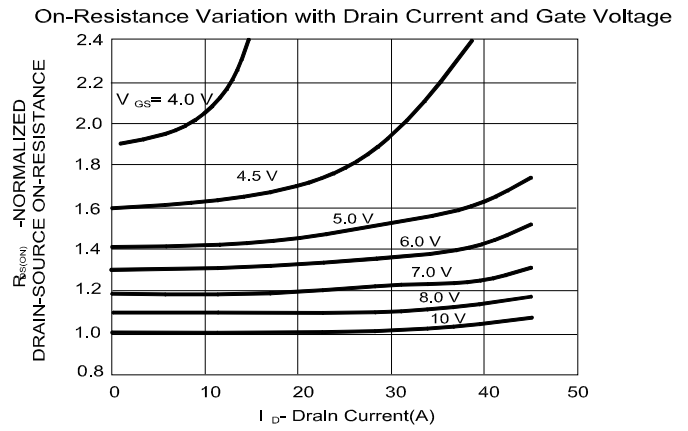
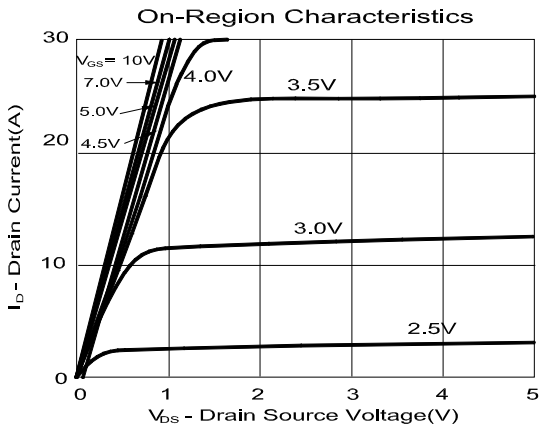
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.7	1.9	2.5	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$			±250	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 32V, V_{GS} = 0V$			1	μA
		$V_{DS} = 30V, V_{GS} = 0V, T_C = 125\text{ °C}$			10	
On-State Drain Current <sup>1</sup>	$I_{D(ON)}$	$V_{DS} = 10V, V_{GS} = 10V$	70			A
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(ON)}$	$V_{GS} = 5V, I_D = 10A$		27	45	mΩ
		$V_{GS} = 10V, I_D = 12A$		21	25	

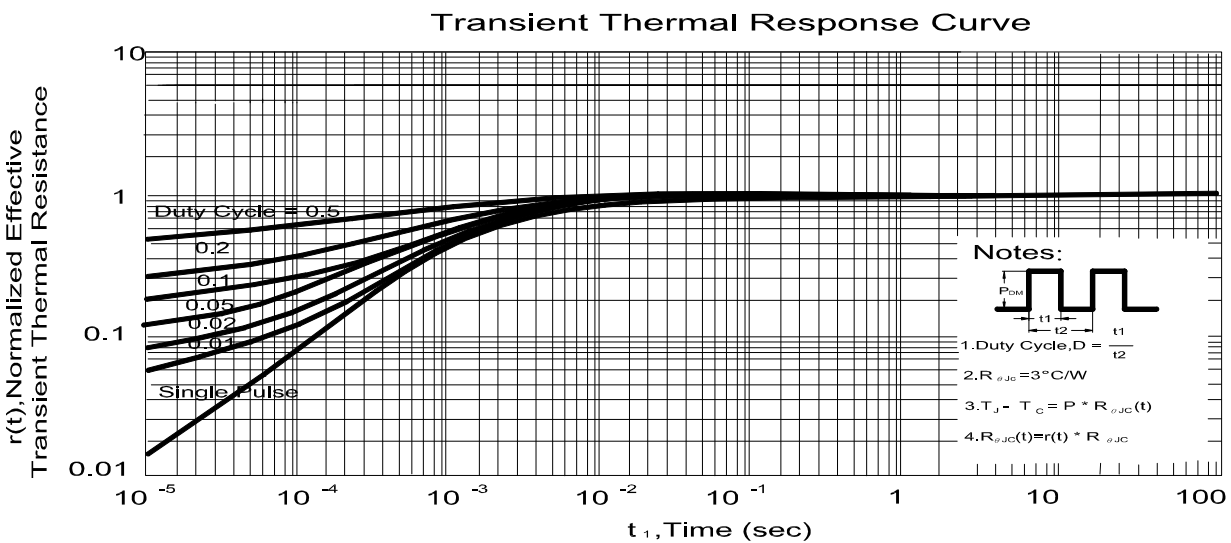
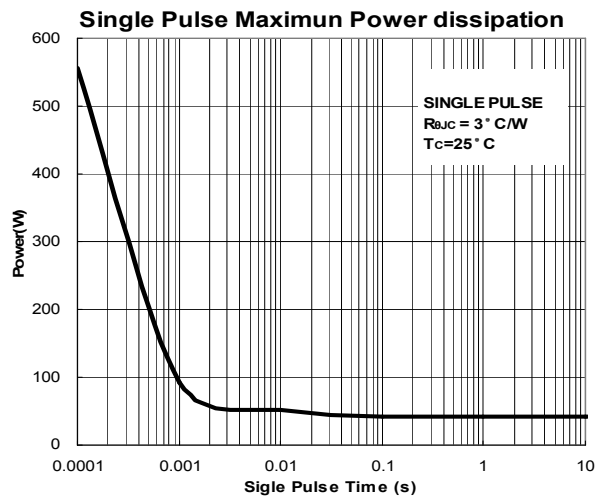
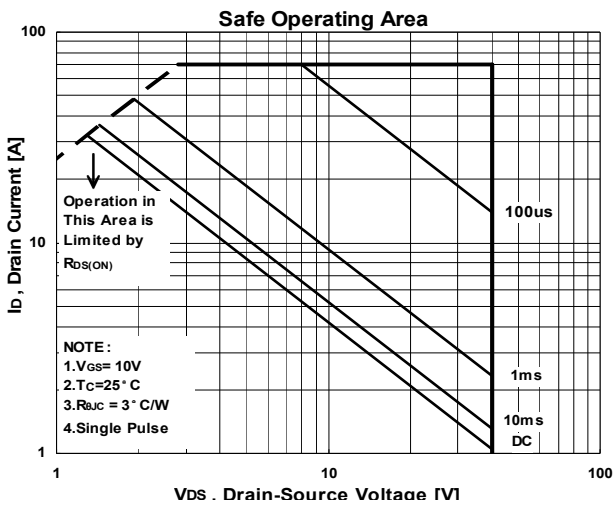
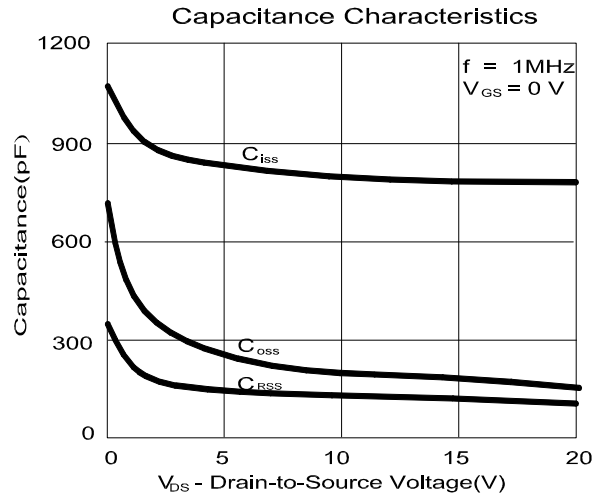
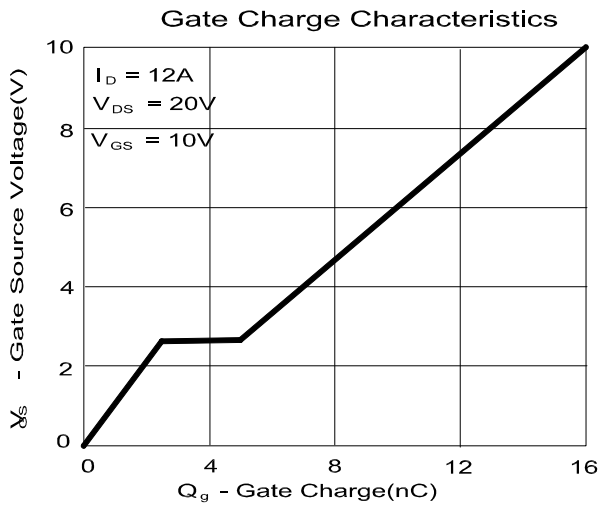
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = 10V, I_D = 12A$		18		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 20V, f = 1MHz$		760		pF
Output Capacitance	$C_{oss}$			165		
Reverse Transfer Capacitance	$C_{rss}$			110		
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{DS} = 0.5V_{(BR)DSS}, V_{GS} = 10V, I_D = 12A$		16		nC
Gate-Source Charge <sup>2</sup>	$Q_{gs}$			2.5		
Gate-Drain Charge <sup>2</sup>	$Q_{gd}$			2.1		
Gate Resistance	$R_g$	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		1.5	3	$\Omega$
Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$	$V_{DS} = 20V, R_L = 1\Omega, I_D \cong 1A, V_{GS} = 10V, R_{GEN} = 6\Omega$		2.1	4.2	nS
Rise Time <sup>2</sup>	$t_r$			7.2	14	
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$			11.6	21.0	
Fall Time <sup>2</sup>	$t_f$			3.5	7.2	
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ C</math>)</b>						
Continuous Current	$I_S$				32	A
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = 12A, V_{GS} = 0V$			1.2	V
Reverse Recovery Time	$t_{rr}$	$I_F = 5 A, di_F/dt = 100A / \mu S$		14.5		nS
Reverse Recovery Charge	$Q_{rr}$			7.2		nC

<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu sec$ , Duty Cycle  $\leq 2\%$ .

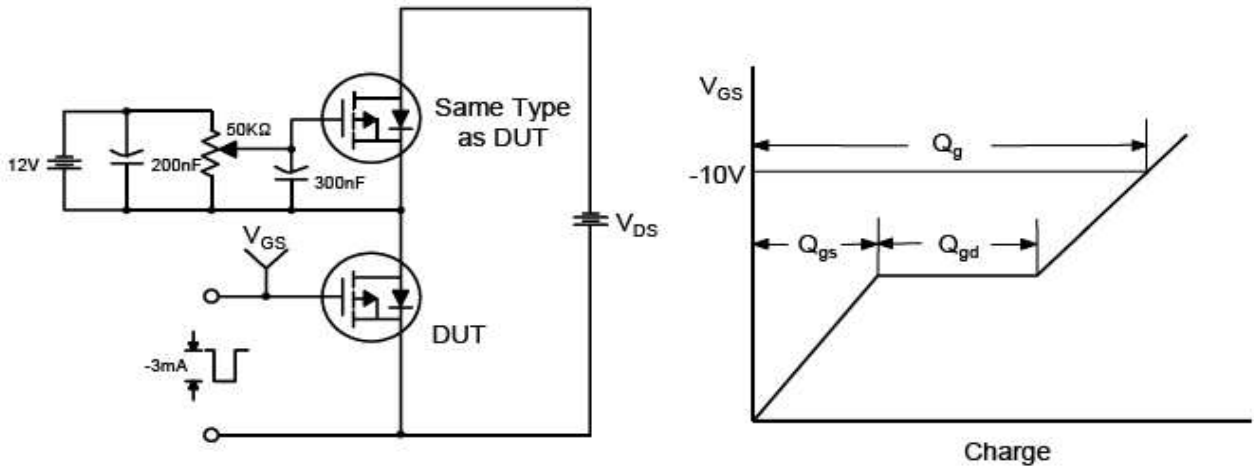
<sup>2</sup>Independent of operating temperature.

**REMARK: THE PRODUCT MARKED WITH "P2504BDG", DATE CODE or LOT #**

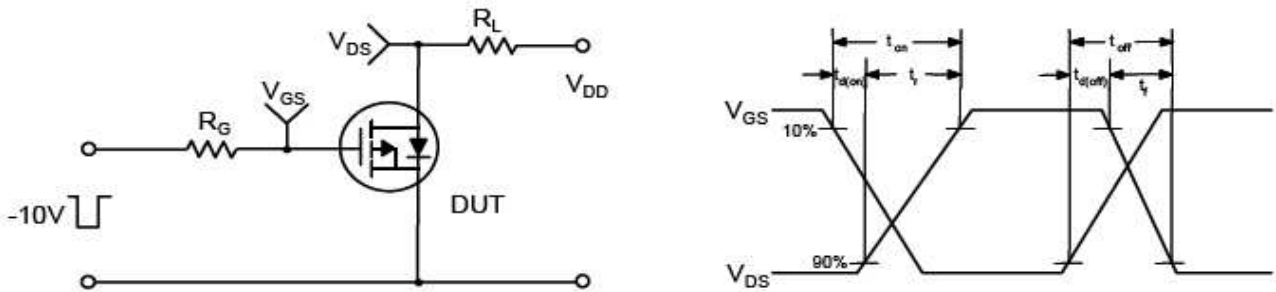




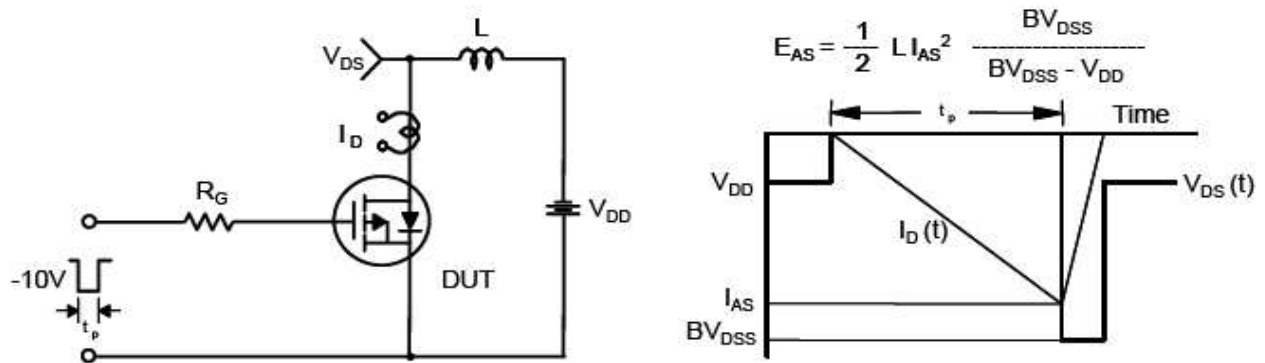
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

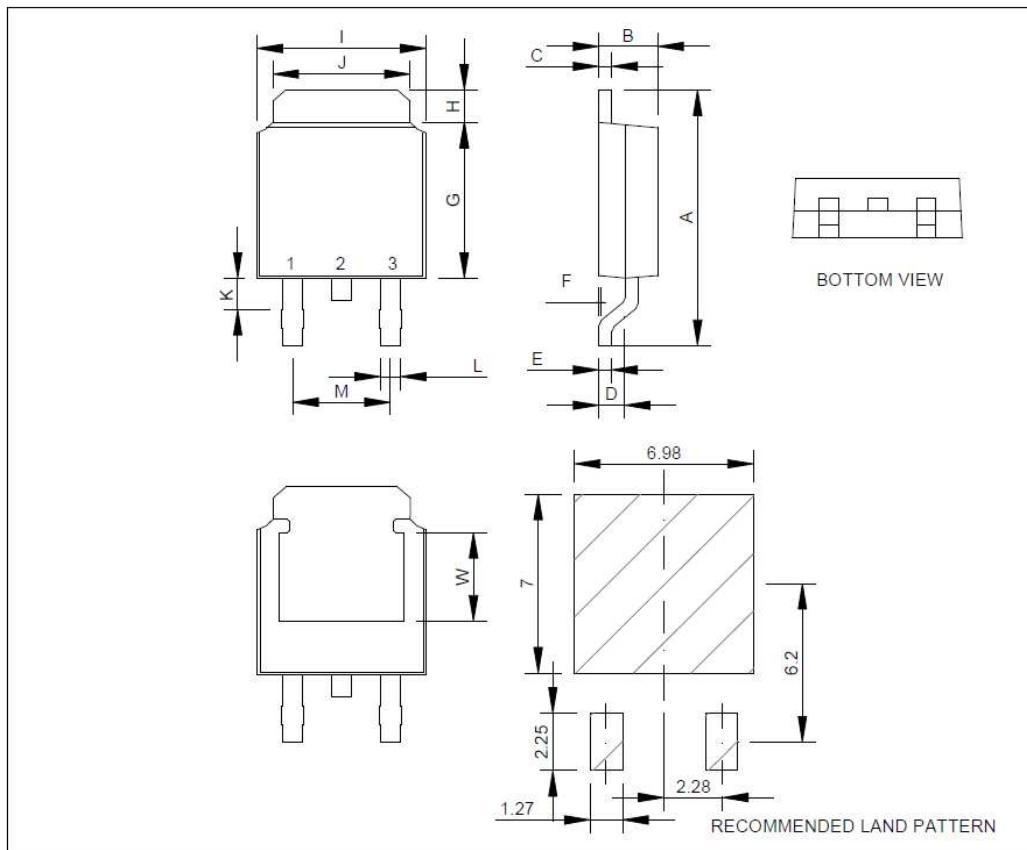


Unclamped Inductive Switching Test Circuit & Waveforms



**TO-252 (DPAK) MECHANICAL DATA**

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	8.9	9.5	10.4	H	0.8	1.27	2.03
B	2.19	2.3	2.435	I	6.35	6.6	6.8
C	0.35	0.5	0.65	J	4.8	5.34	5.5
D	0.89		1.5	K	0.5		1.5
E	0.35		0.65	L	0.4	0.76	0.89
F	0.0		0.23	M	3.96		5.18
G	5.4		6.2	W	3.38	3.58	3.78



**TO-252 (DPAK) MECHANICAL DATA 散熱片**

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
S	4.57	5.249	5.6	U	1.4		3
T	3.81	4.064	5	V	0.95		1.1

